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**(54) JET PLATING DEVICE**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To uniformly regulate the thickness of plating coating in the face of a wafer by forming the flows of plating solns. different in the center part and the outer circumferential part of a semiconductor substrate in a cup tank in which plating solns. from a plating tank are jetted.

**SOLUTION:** The cup tank has an internal and external double structure of a cup tank 5A on the outer circumferential side and a cup tank 5B arranged on the center part of the cup tank 5A. Then, through the space between the internal and external cup tanks 5A and 5B, the flow of a plating soln. orientated toward the outer circumferential part 1a of a wafer 1 is formed, and also, through the inside of the cup tank 5B on the inside, the flow of a plating soln. orientated toward the center part 1b of the wafer 1 is formed independently of the above flow of

the plating soln. A plating soln. 9 in a plating tank 7 is fed to the jet port 13 of the cup tanks 5A and 5B by pumps 10A and 10B controlled by inverters. In this way, plating can be executed while the flow rates of the plating solns. are independently controlled, and, even, as for the coating with  $\leq 1 \mu\text{m}$  coating thickness, the uniform one can be obtd.

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